

Low_Power TEC Driver - PMP9759

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C2, C3, C5, C6	4	10uF	CAP, CERM, 10uF, 6.3V, +/-20%, X5R, 0603	0603	GRM188R60J106ME84	MuRata
C1, C4	4	2.2uF	CAP, CERM, 2.2uF, 6.3V, +/-20%, X5R, 0402	0402	GRM155R60J225ME15D	MuRata
C8	1	0.1uF	CAP, CERM, 0.1uF, 16V, +/-10%, X5R, 0603	0603	GRM188R61C104KA01D	MuRata
L1	1	1.5uH	Inductor, Shielded, Composite, 1.5uH, 4A, 0.3 ohm, SMD	4.0x4.0x2mm	XFL4020-152MLB	Coilcraft
R1, R4	2	1M0	RES SMD 1M OHM 1% 1/10W 0603	0603	CRCW06031M00FKEA	Vishay-Dale
R2	1	130k	RES SMD 130K OHM 1% 1/10W 0603	0603	CRCW0603130KFKEA	Vishay-Dale
R3	1	750k	RES SMD 750K OHM 1% 1/10W 0603	0603	CRCW0603750KFKEA	Vishay-Dale
U1	1		High Efficiency Single Inductor Buck-Boost Converter w/ 4-A Switches	DSJ	TPS63020DSJT	Texas Instruments

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